IN THE CLAIMS

This listing of claims will replace all prior versions, and listings, of claims in the application:

1 1. (Currently Amended) A method of forming a spin valve sensor, comprising: 2 forming a first pinned layer with a top surface, bottom surface and sides orthogonal to 3 the top and bottom surface and having a first magnetic orientation and a first width; 4 forming a second pinned layer with sides orthogonal to the top and bottom surface of 5 the first pinned layer and having a second magnetic orientation anti-parallel to the first 6 magnetic orientation and a second width; and 7 forming a sensing layer with sides orthogonal to the top and bottom surface of the 8 first pinned layer and having a second third width smaller than the first width; and 9 forming a spacer layer with sides orthogonal to the top and bottom surface of the first 10 pinned layer and having a width equal to the second width; 11 wherein the third width is selected to coincide with a predetermined track width, the first width being selected to be wider than the predetermined track width. 2. (Withdrawn) The method according to Claim 1, further comprising forming 1 2 a coupling layer disposed between the first and second pinned layers. (Withdrawn) The method according to Claim 2, wherein the first and second 3. 1 2 pinned layers are formed with substantially equal thickness. (Withdrawn) The method according to Claim 3, wherein forming the first 1 4. and second pinned layers creates self-pinned magnetic orientations. 2

5. 1 (Withdrawn) The method according to Claim 3, further comprising 2 depositing an anti-ferromagnetic material (AFM) adjacent to the first pinned layer, wherein a thickness of the AFM creates exchange coupling between the AFM and the first pinned layer. 3 1 6. The method according to Claim 1, wherein forming the sensing (Original) 2 layer includes: 3 forming a free layer having a third magnetic orientation orthogonal to the first 4 and second magnetic orientations; 5 forming a bias layer in proximity to the free layer having a fourth magnetic orientation anti-parallel to the third magnetic orientation; and 6 7 forming an AFM layer adjacent to the bias layer, wherein exchange coupling 8 between the AFM layer and the bias layer sets the fourth magnetic orientation. 7. 1 (Original) The method according to Claim 6, wherein the bias layer is 2 formed with a thickness greater than a thickness of the free layer. 8. 1 (Currently Amended) The method according to Claim 1, wherein the second 2 pinned layer is formed with a width substantially equal to the second third width. 9. (Original) The method according to Claim 8, wherein insulating layers are 1 2 disposed on both sides of the second pinned layer. 1 10. (Original) The method according to Claim 1, wherein the second pinned 2 layer is formed with a width substantially equal to the first width.

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- 1 11. (Original) The method according to Claim 1, wherein insulating layers are
- 2 disposed on both sides of the sensing layer.